



Qualcomm Incorporated

5775 Morehouse Drive, San Diego, CA 92121

20 March 2023

Mr. Maurice Pope
Ms. Susanna Kooistra
ETSI, MCC
650, route des Lucioles
06921 Sophia Antipolis CEDEX
France

Subject: Nomination of candidate for the 3GPP TSG SA WG2 Vice-Chair

Dear Mr. Pope and Ms. Kooistra:

I am pleased to inform you that Qualcomm Incorporated, through its ATIS 3GPP affiliation, is nominating Dario Serafino Tonesi as candidate for the position of 3GPP TSG SA WG2 Vice-Chair at the upcoming election in SA2#157 in Berlin, Germany.

Dario is informed about and aware of the antitrust/competition laws and regulations of relevant jurisdictions, and if elected, he will comply with such laws while acting in his capacity as TSG SA WG2 Vice-Chair.

In proposing Dario for the position of 3GPP TSG SA WG2 Vice-Chair, Qualcomm will fully support him in the role. Qualcomm remains fully committed to the success of 3GPP and its diverse ecosystem.

A brief curriculum vitae of Dario is provided as a separate document.

Best Regards,

A handwritten signature in black ink, reading "Edward G. Tiedemann, Jr.", with a stylized flourish at the end.

Dr. Edward G. Tiedemann, Jr.
Senior Vice-President, Engineering
Qualcomm and IEEE Fellow
Qualcomm Technologies, Inc.



Dario Serafino Tonesi



Dario Serafino Tonesi received his Ph.D. in Information Engineering and his M.Sc. degree in Electronic Engineering from the Università degli Studi di Brescia (Brescia, Italy) in 2008 and in 2004, respectively. Previously, in 2003 he received his M.Sc. degree in Electrical and Computer Engineering from the Georgia Institute of Technology (Metz, France, and Atlanta, GA, USA).

Dario has 13 years of experience in telecommunications in leading telecom companies.

Between the end of 2009 and 2016, he was a 3GPP RAN3 delegate at Nokia/Nokia Siemens Networks in Wrocław, Poland, where he worked on 3G and LTE femto cells, UMTS/LTE and LTE/Wi-Fi interworking and was the rapporteur of, among others, the 3GPP specifications for S1AP, RAN and HNB Stage 2.

In 2016, Dario started working as a 3GPP SA2 delegate for Huawei in Berlin, Germany. In that role, he was the rapporteur of the study items on enhancements for multicast/broadcast systems (FS_5MBS, in 2019-2020) and on enhancements to ProSe UE-to-Network Relay (FS_REAR, in 2016-2017). In addition, he was working on V2X, CIoT and support for enhanced TV services.

Dario joined Qualcomm's SA2 delegation in 2020. Since then, he has been working on Access Traffic Steering Switching and Splitting (ATSSS), Edge Computing and on support for eXtended Reality (XR) services, topics that allowed him to participate also in a few 3GPP SA plenary e-meetings. He is currently based in San Diego, CA, USA.